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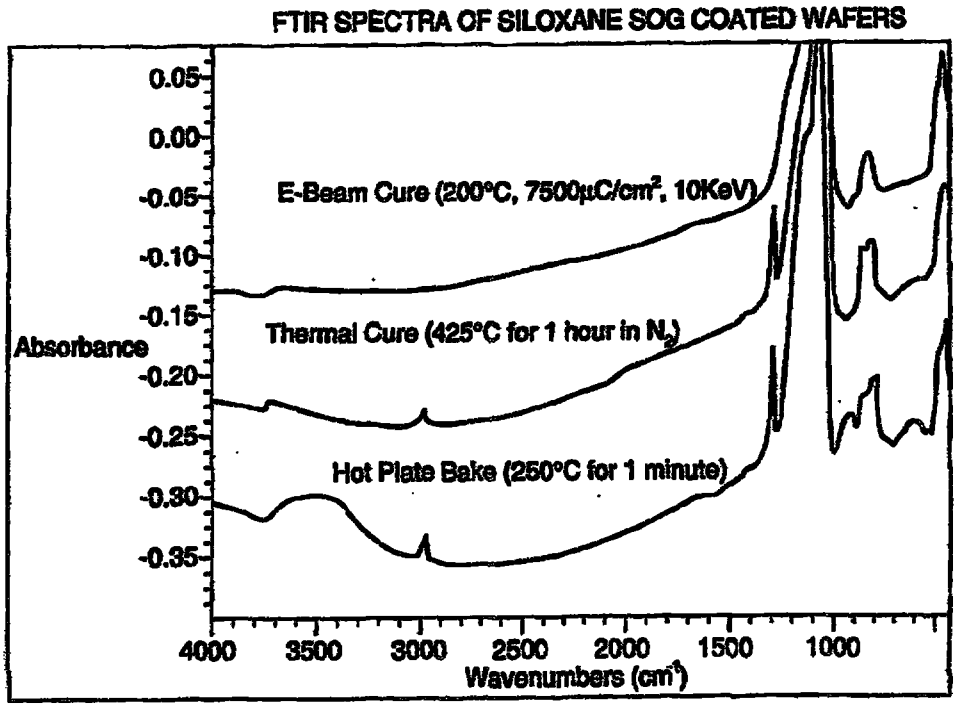
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(54) Title: ELECTRON-BEAM PROCESSED FILMS FOR MICROELECTRONICS STRUCTURES



(57) Abstract

An improved method for producing substrates coated with dielectric films for use in microelectronic applications wherein the films are processed by exposing the coated substrate surfaces to a flux of electron beam. Substrates cured via electron beam exposure possess superior dielectric properties, density, uniformity, thermal stability, and oxygen stability.